

Notice of References CitedApplication No.
09/259,849Applicant(s)
FarrarExaminer
Bernard SouwGroup Art Unit
2814

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		DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
	A	5,913,147 ✓	06/1999	Dubin et al.	438	687
	B	5,969,422 ✓	10/1999	Ting et al.	257	762
	C	5,968,333 ✓	10/1999	Nogami et al.	205	184
	D	5,933,758 ✓	08/1999	Jain	438	687
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	L	5,662,788 ,	09/1997	Sandhu et al.	205	87
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NON-PATENT DOCUMENTS

		DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
	U	Chakravorty et al., "High-Density Interconnection Using Photosensitive Polyimide and Electroplated Copper Conductor Lines". IEEE Trans.Comps. Hybrids and Manuf. technology, 13/1, 1990, pp.200206	04/1990
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